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# Low noise charge amplifiers in submicron CMOS

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# Outline

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- I. Design methodology for low noise preamplifiers in submicron CMOS**
  
- II. Design example: PET front end in 0.18 $\mu\text{m}$  CMOS**

# Design Methodology

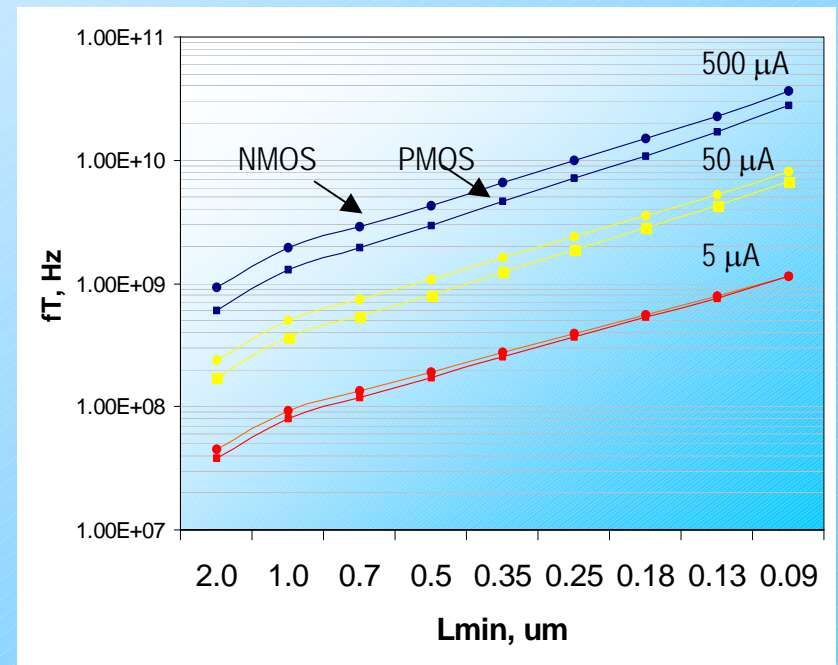
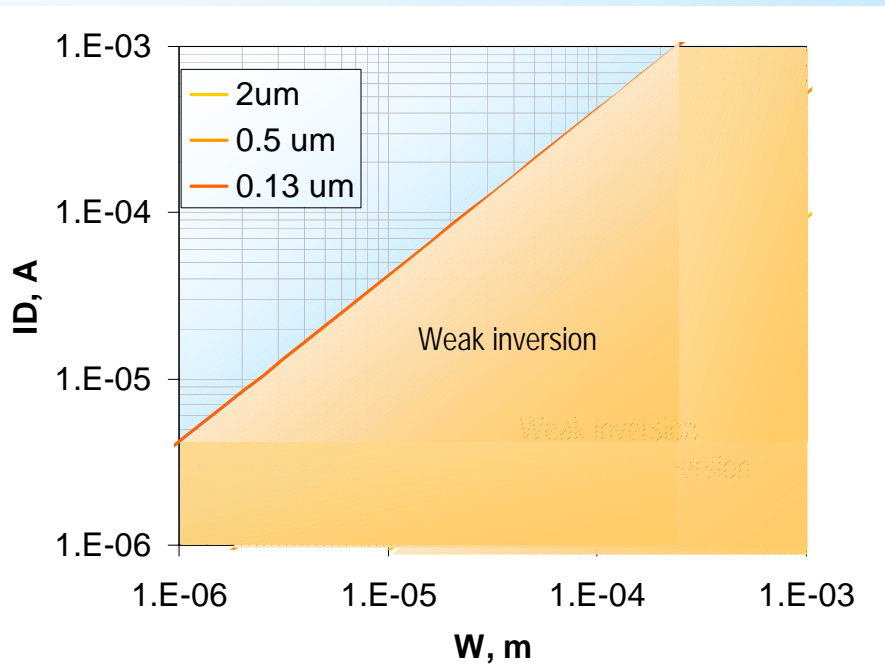
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1. System specifications
2. Technology choice
3. Noise properties of transistors
4. **Hand calculate input MOSFET for minimum ENC**
5. Design rest of preamplifier
6. Design remaining amplifier stages & bias circuits
7. SPICE simulate analog core
8. Design digital functions (if any)

# Increasing importance of moderate inversion

- Linear current density  $I_D/W$  for moderate inversion increases by a factor of 10 every 2 CMOS generations.

- Submicron devices have high  $f_T$  even at low current.
- Also moderate inversion allows operation at low  $V_{DS}$ .



$$W/L = 100; L=L_{\text{min}}$$

# Dimensioning the input MOSFET for minimum ENC

Series noise “capacitive match” problem:

$$ENC^2 = ENC_{sw}^2 + ENC_f^2$$

$$ENC_{sw}^2 = \frac{a_1}{2\tau_p} e_{n,sw}^2 (C_d + C_{in})^2$$

$$e_{n,sw}^2 = \frac{4kTn\gamma}{g_m}$$

$$ENC_f^2 = a_2\pi \frac{K_F}{C_{ox}WL} (C_d + C_{in})^2$$

$\gamma$  and  $g_m$  depend on region of operation:

	$\gamma$	$g_m$
weak	1/2	$qI_D / nkT$
strong	2/3	$\sqrt{2\mu C_{ox} \frac{W}{L} I_D}$

*How to handle moderate inversion?*

G.De Geronimo, P.O'Connor, V. Radeka and B. Yu, “Front-end electronics for imaging detectors”, *Nuclear Instrum. Methods* A471 (2001) 192-199

P. O'Connor and G.De Geronimo, “Prospects for charge sensitive amplifiers in scaled CMOS”, *Nuclear Instrum. Methods* A484 (2002) 713-725

L. Fabris, P. Manfredi, “Optimization of front-end design in imaging and spectrometry applications with room temperature semiconductor detectors”, *IEEE Trans Nucl. Sci.*, 49 (4), 1978–1985, Aug. 2002

M. Manghisoni, L. Ratti, V. Re, and V. Speziali, “Submicron CMOS Technologies for Low-Noise Analog Front-End Circuits”, *IEEE Trans. Nucl. Sci.* 49,1783-1790, Aug. 2002

# Simplified EKV model for hand calculations

- substrate-referenced compact MOS model
- small, physics-based parameter set
- continuous modeling of weak to strong inversion
- simple set of equations valid for saturation:

Inversion coefficient  $i = I_D / I_0$

$$I_0 = 2n\beta \cdot U_T^2 \quad \beta = \mu \cdot C_{ox} \frac{W}{L} \quad U_T = \frac{kT}{q}$$

Interpolation function :

$$f(i) = \frac{1}{2} (\sqrt{1+4i} + 1)$$

short-channel effects not modeled



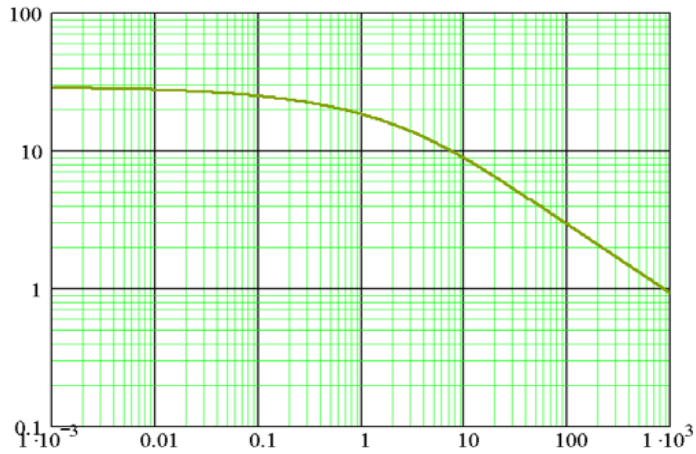
$$\frac{g_m}{I_D} = \frac{1}{n \cdot U_T} \frac{1}{f(i)}$$

$$\frac{C_{GS}}{WLC_{ox}} = \frac{1}{\frac{3}{2} + \frac{f(i)}{i}}$$

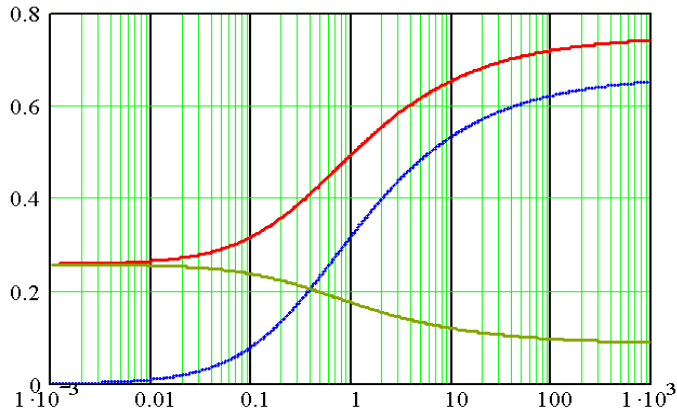
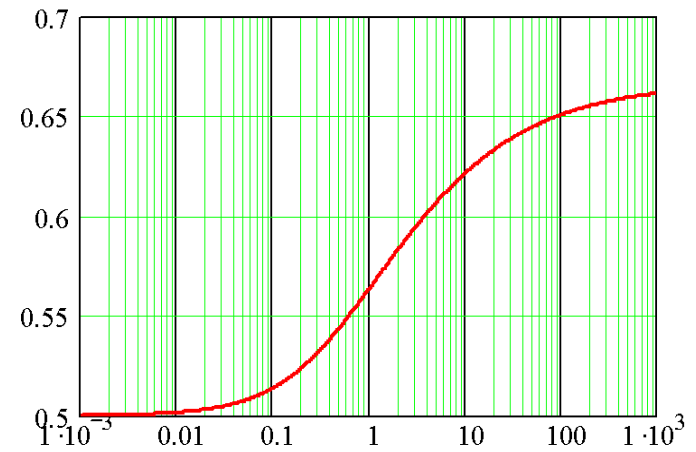
$$\frac{S_{th}}{4kTng_m} = \frac{\frac{1}{2} + \frac{2}{3}i}{1+i} \equiv \gamma$$

# EKV results

$g_m/I_D$  vs.  $i$

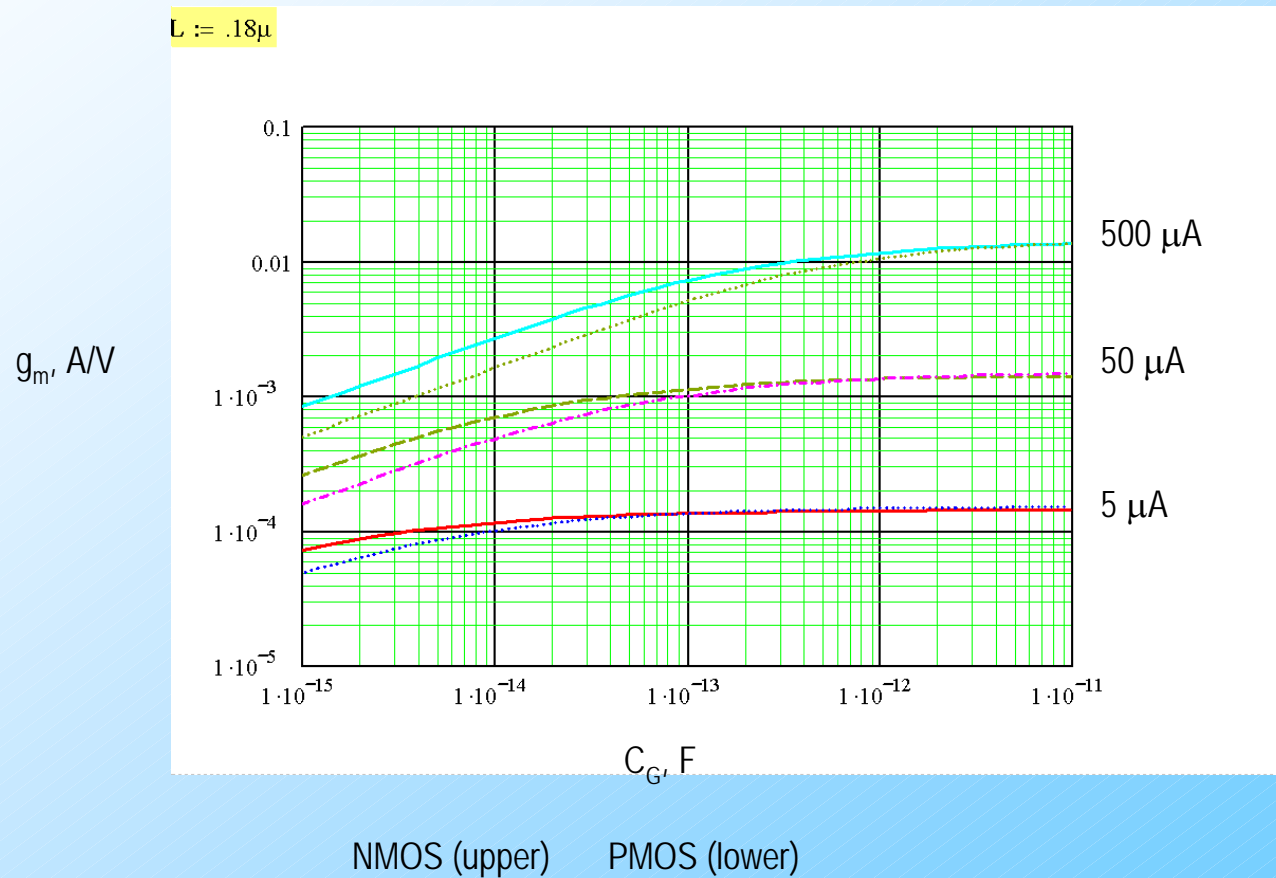


$\gamma$  vs.  $i$



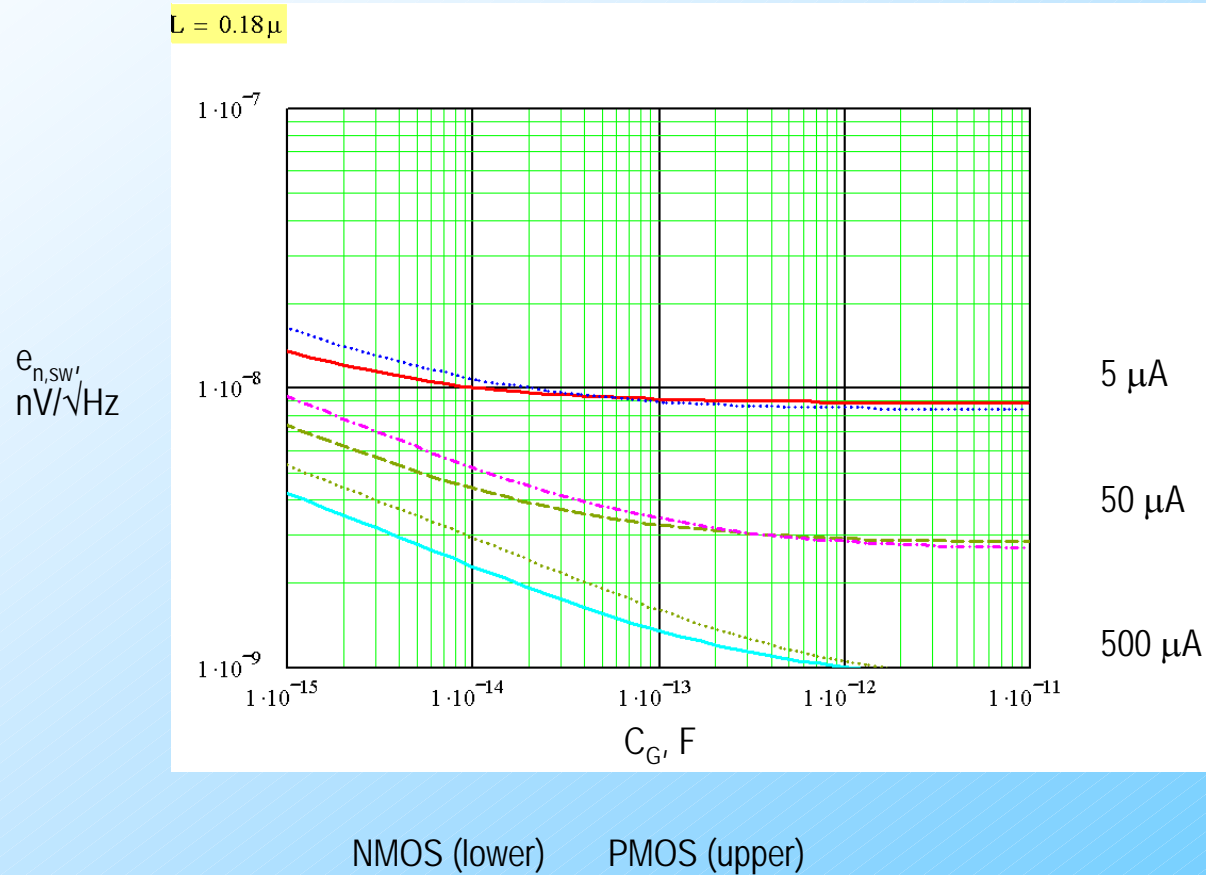
$C_{gs}$ ,  $C_{gb}$ ,  $C_{in}$  vs.  $i$

# $g_m$ vs. $C_G$ vs. scaling

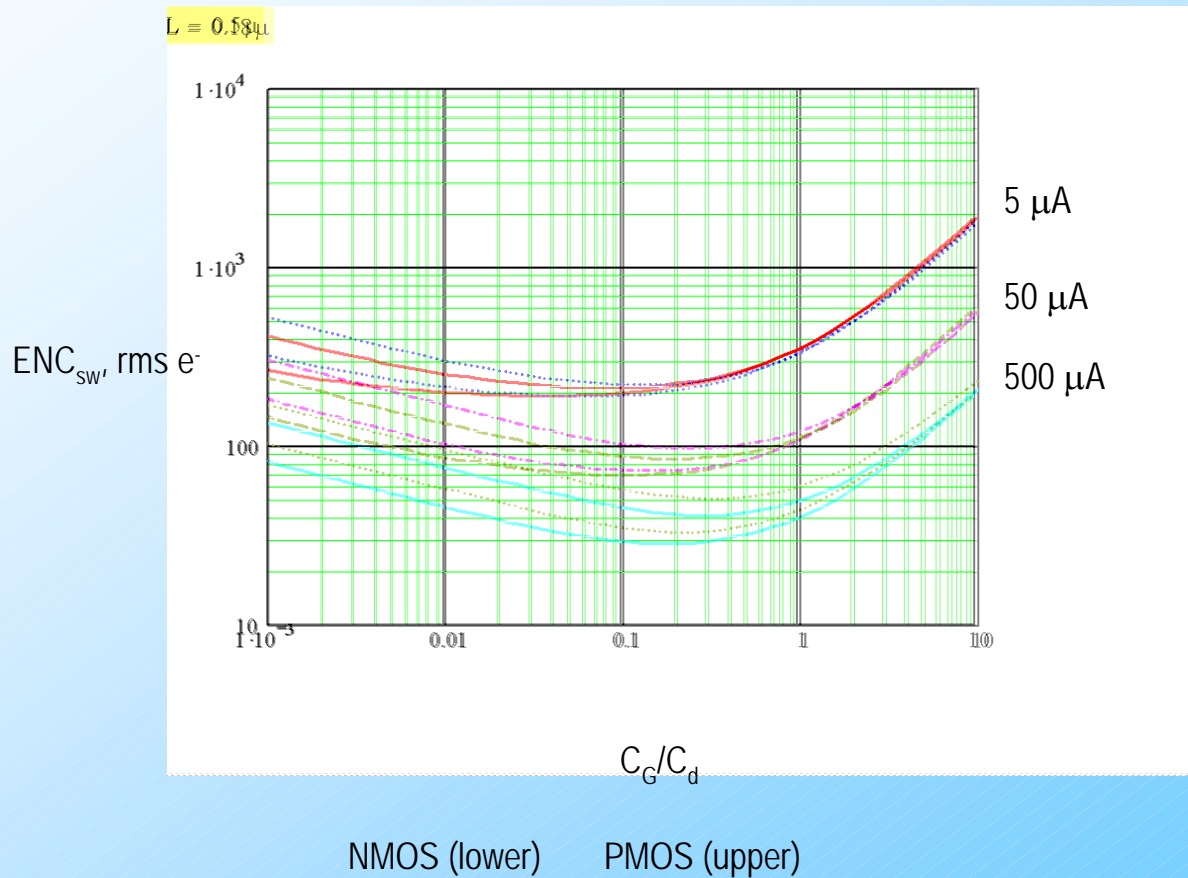




# $e_n$ vs. $C_G$ vs. scaling



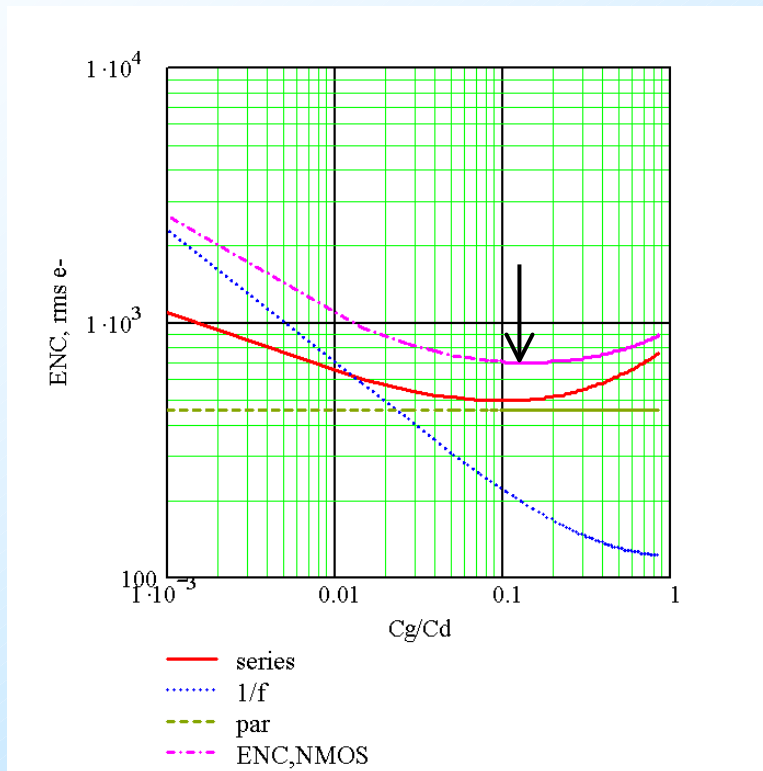
# White series noise vs. $C_G/C_d$ vs. scaling



# Device width for minimum ENC

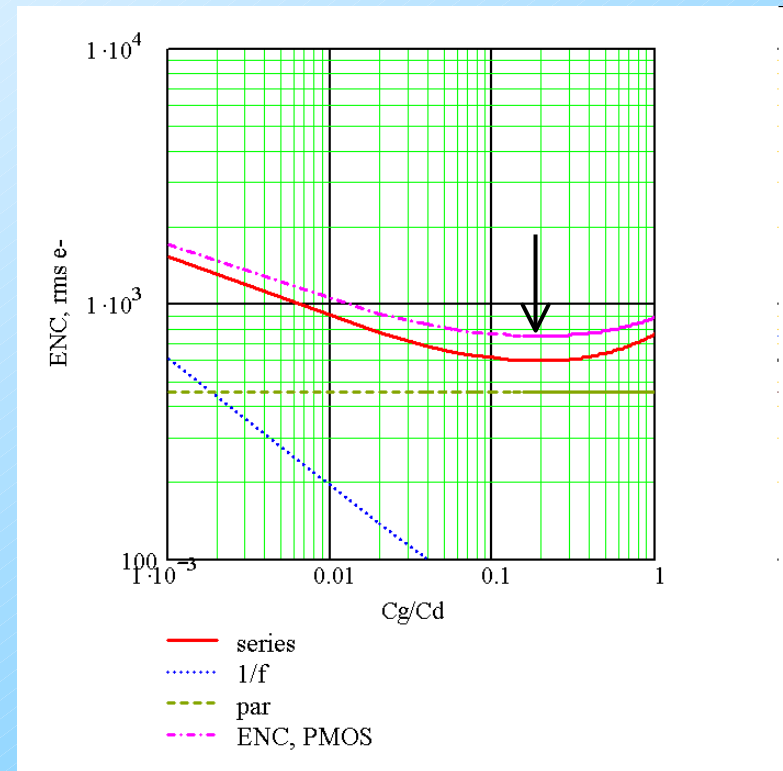
0.18 CMOS,  $t_p=70\text{ns}$ ,  $P=1\text{mW}$ ,  $I_{\text{leak}}=250\text{nA}$ ,  $C_d=20\text{pF}$ ,  $KF_n=10^{-24}\text{J}$ ,  $KF_p=10^{-25}\text{J}$

## NMOS



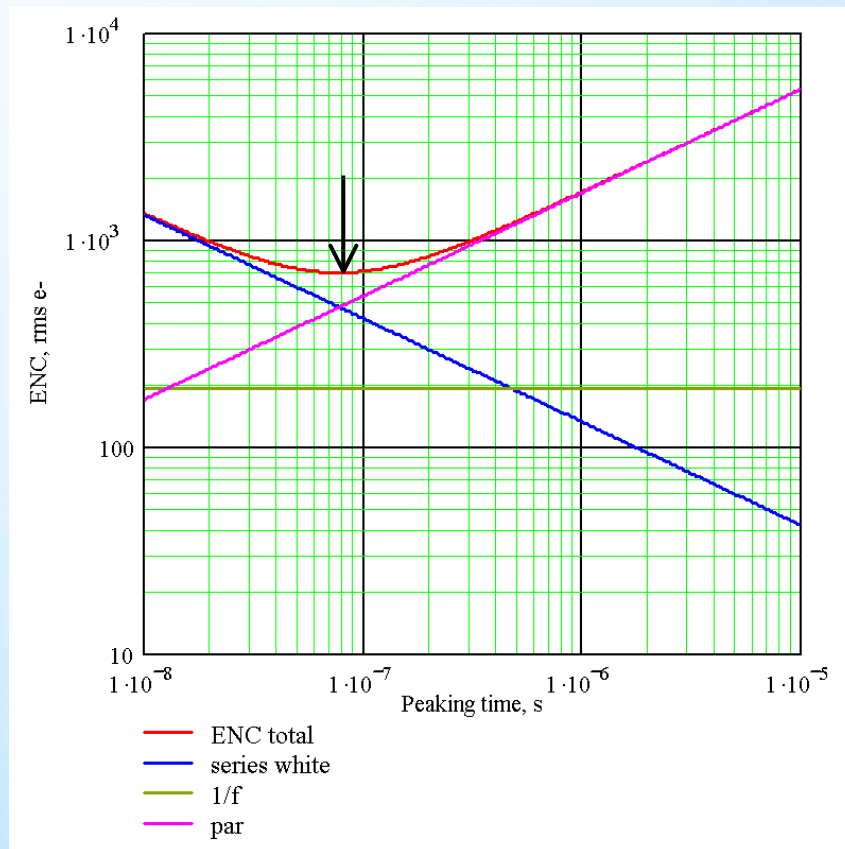
$$\begin{aligned} ENC_{\min} &= 697 e^- \\ C_{\text{gopt}} &= 0.14 C_d \\ IC &= 0.136 \end{aligned}$$

## PMOS



$$\begin{aligned} ENC_{\min} &= 748 e^- \\ C_{\text{gopt}} &= 0.19 C_d \\ IC &= 0.316 \end{aligned}$$

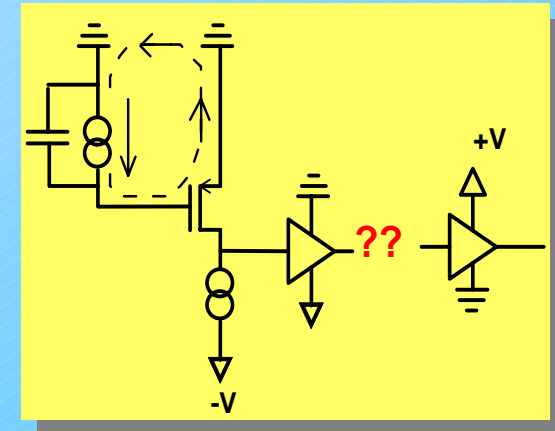
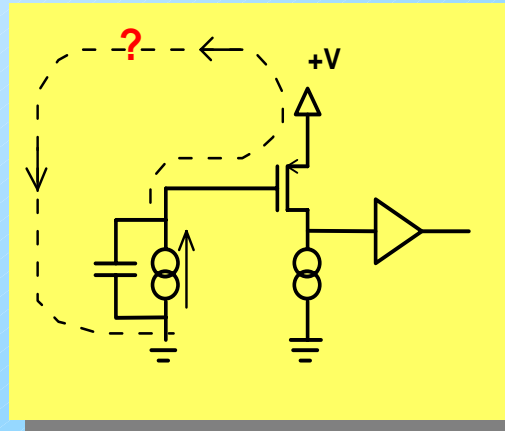
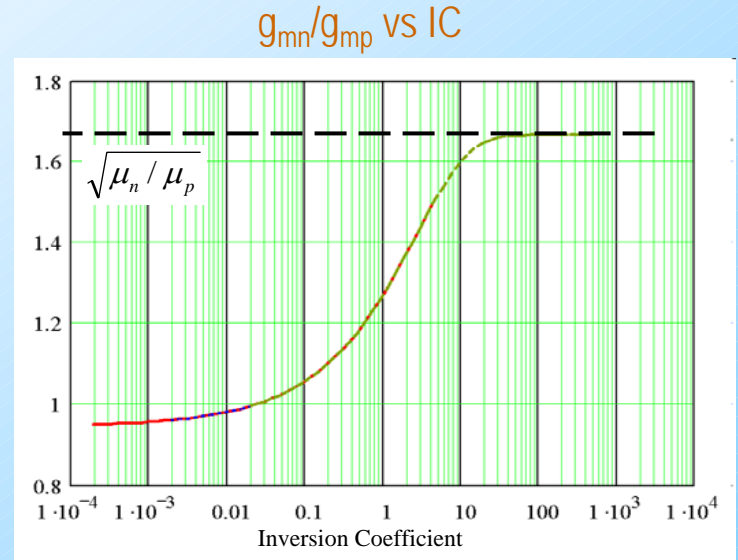
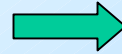
# Noise vs. peaking time for optimized device



NMOS 1694/0.2,  $t_p=70\text{ns}$ ,  
 $I_D=550\mu\text{A}$ ,  
 $I_{\text{leak}}=250\text{nA}$ ,  $C_d=20\text{pF}$   
 $KF_n=10^{-24}\text{J}$

# Choice of PMOS vs. NMOS

- PMOS lower 1/f noise
- NMOS white series noise advantage over PMOS diminishes each generation
- PMOS can be operated at reverse  $V_{BS}$  to reduce bulk resistance noise
- PMOS lower tunneling current at ultra-thin  $t_{ox}$
- Single-supply operation of PMOS-input preamp awkward:

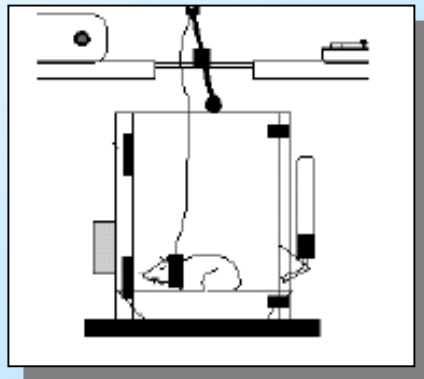


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## II. Design example: PET front end in 0.18 $\mu\text{m}$ CMOS

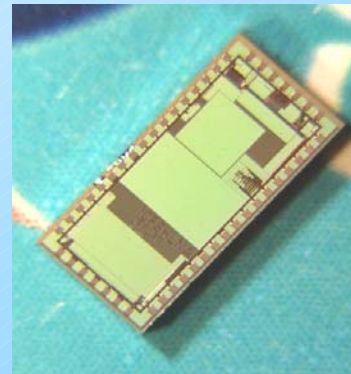
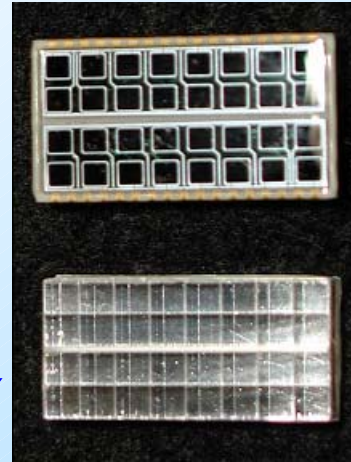
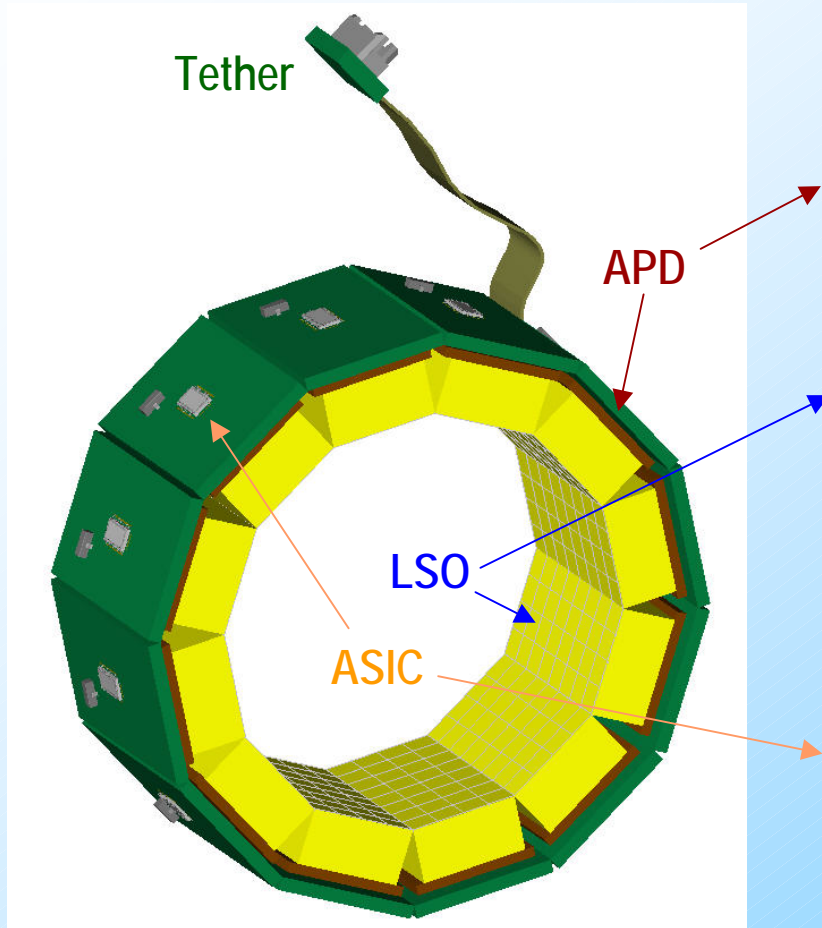
# RatCAP: Rat Concious Animal PET

Head-mounted tomograph to image the brain of an unanesthetized, freely moving animal



Mockup of the portable ring on the head of a rat

# Tomograph Ring



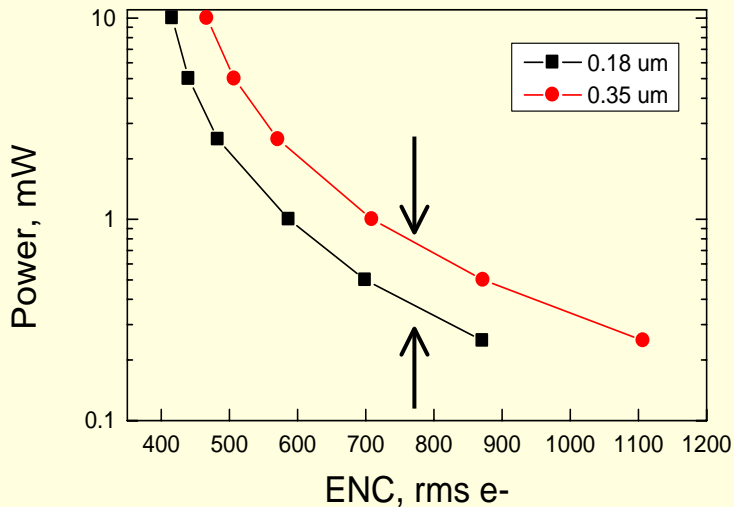
- 4 cm ring containing 12 block detectors (LSO/APD)
- 384 or 768 channels
- 15 Mcps rate for full ring
- 150g total weight
- 1.5W power on ring
- flexible and lightweight cable for signals, power, HV



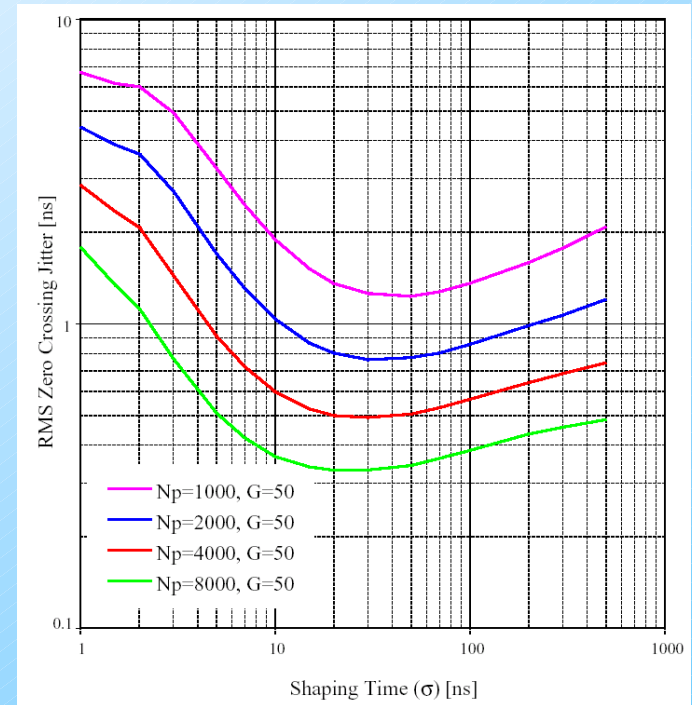
# Technology choice

- 0.35 and 0.18  $\mu\text{m}$  available
- Critical requirement: low power and low noise
- Dynamic range low

## Preamp power vs. ENC



## Time jitter vs. shaping time

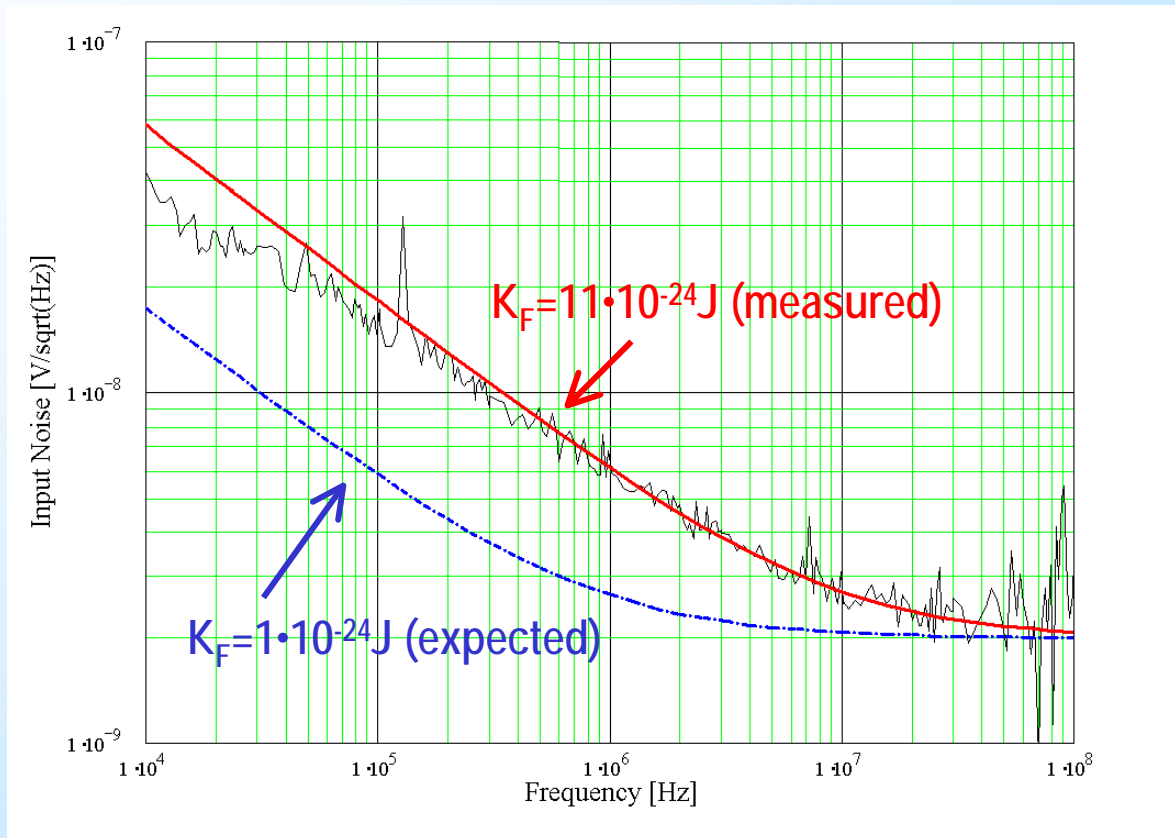


• LSO decay 40 ns

•  $e_n \sim 1 \text{ nV}/\sqrt{\text{Hz}}$

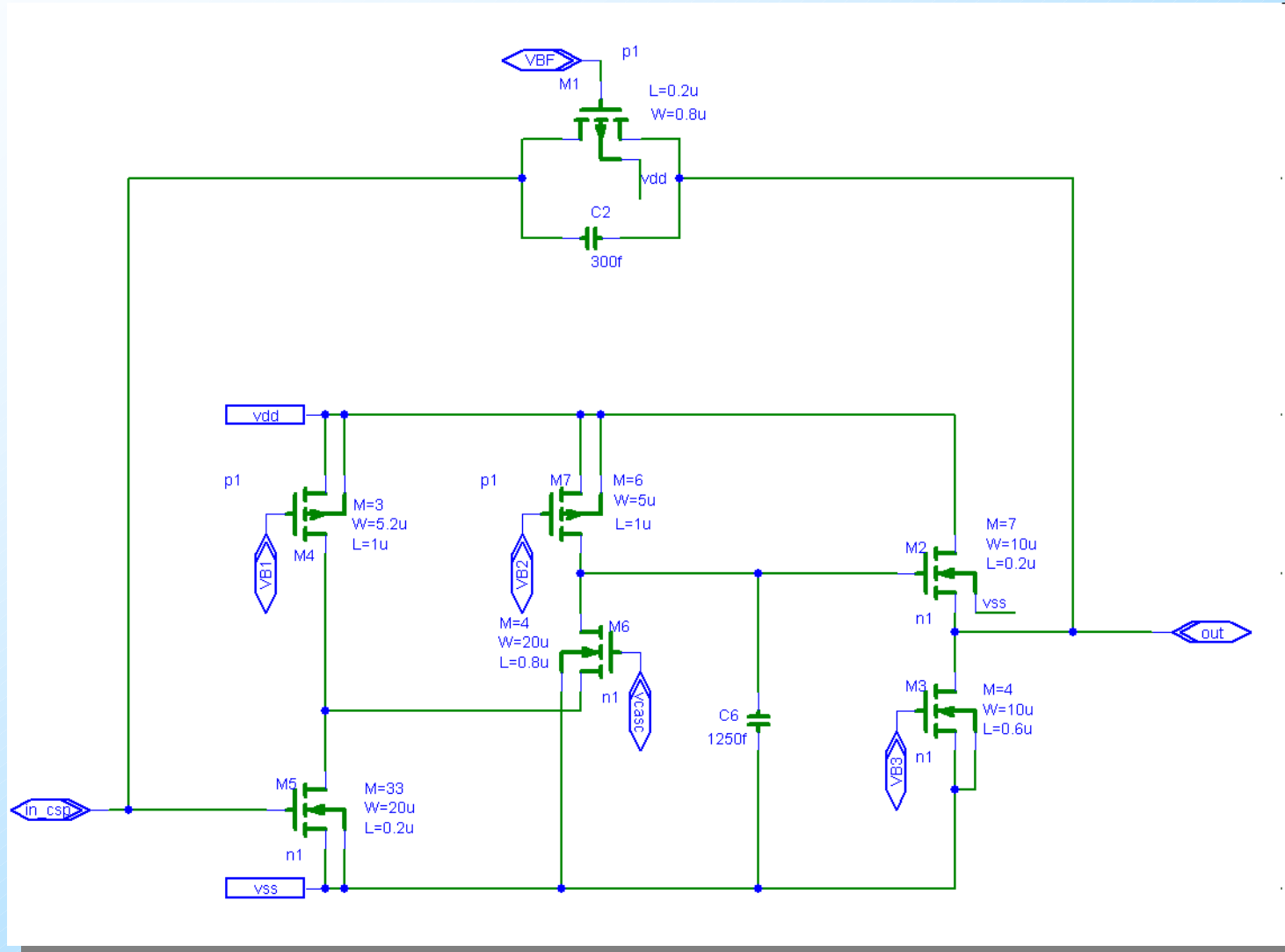
B. Yu

# NMOS noise measurement



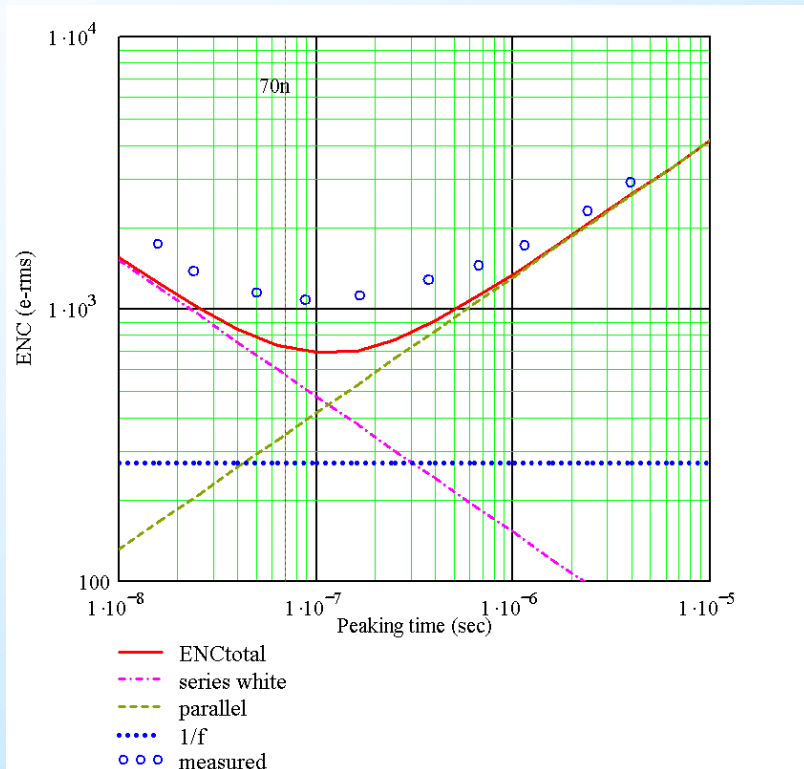
- unexpectedly large  $1/f$  noise found for this technology.
- preamp ENC 32% higher than predicted.
- re-optimizing  $W$  for better noise balance could save 11%.
- PMOS a better choice?

# Preamplifier schematic



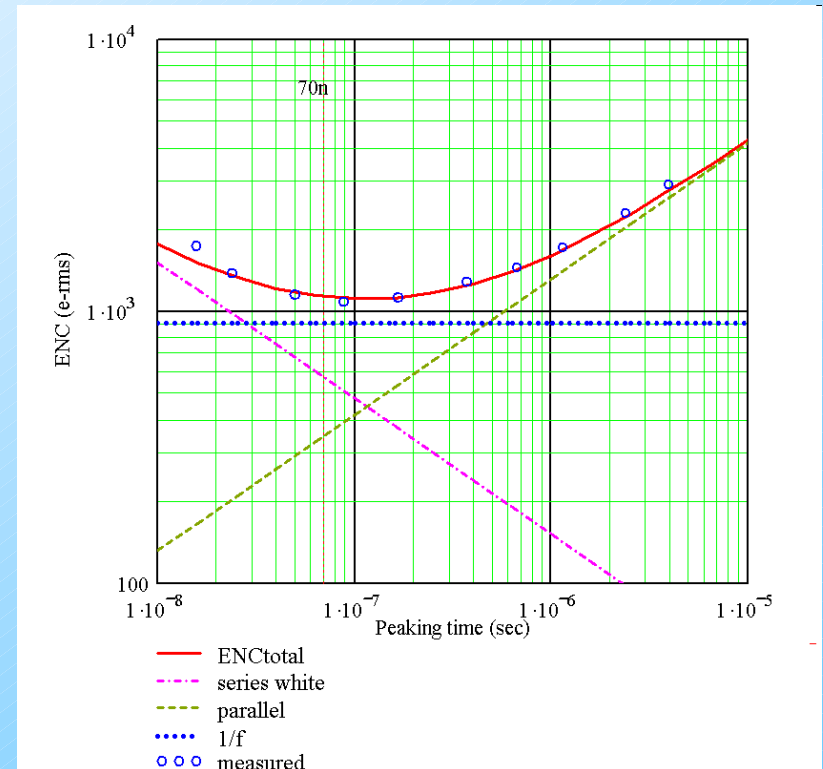
# Simulated and measured preamp ENC

## Preamp ENC vs. shaping time



simulated with  $K_F = 10^{-24} \text{ J}$

$W=33 \times 20/0.2, I_D=550\mu\text{A}, R_G=3, R_B=100$



simulated with  $K_F = 11 \times 10^{-24} \text{ J}$

# Conclusions

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- moderate and weak inversion bias points become more prevalent in submicron CMOS
- simplified EKV model for preliminary design:
  - continuous modeling of the weak-strong inversion transition
  - small parameter and equation set
  - solves “capacitive match” for series white noise
  - simple way to study effects of MOS scaling
- PMOS input device usually lower noise than NMOS but practical concerns limit usefulness
- low-power PET preamp in 0.18  $\mu\text{m}$  CMOS has been designed
  - unexpectedly high  $1/f$  noise in short-channel NMOS is found in this technology